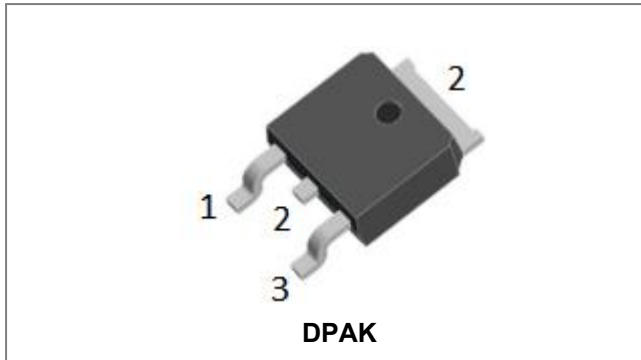


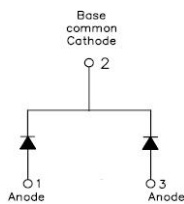
# 12CWQ04FN SCHOTTKY RECTIFIER



## Features

- Small foot print, surface mountable
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Green products in compliance with the ROHS directive
- “-A” is an AEC-Q101 qualified device
- Terminal finish: Tin Lead-free plated
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

## Circuit Diagram



## Applications

- Disk drives
- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection
- Battery charging

## Maximum Ratings(at 25°C unless otherwise specified)

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	-	40	V
Average Rectified Forward Current	$I_{F(AV)}$	$T_C = 120^\circ\text{C}$ , In DC	6(peg leg) 12(peg device)	A
Peak One Cycle Non-Repetitive Surge Current(peg leg)	$I_{FSM}$	8.3 ms, half Sine pulse	84	A

## Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop (per leg) *	$V_{F1}$	@ 6A, Pulse, $T_J = 25^\circ\text{C}$	0.47	0.53	V
	$V_{F2}$	@ 6A, Pulse, $T_J = 125^\circ\text{C}$	0.41	0.48	V
Reverse Current (per leg) *	$I_{R1}$	@ $V_R = \text{rated } V_R$ , $T_J = 25^\circ\text{C}$	0.07	1.0	mA
	$I_{R2}$	@ $V_R = \text{rated } V_R$ , $T_J = 125^\circ\text{C}$	24	40	mA
Junction Capacitance (per leg)	$C_T$	@ $V_R = 5\text{V}$ , $T_C = 25^\circ\text{C}$ $f_{SIG} = 1\text{MHz}$	294	405	pF

\* Pulse width < 300  $\mu\text{s}$ , duty cycle < 2%

**Thermal-Mechanical Specifications:**

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	$T_J$	-	-55 to +125	$^{\circ}\text{C}$
Storage Temperature	$T_{\text{stg}}$	-	-55 to +150	$^{\circ}\text{C}$
Typical Thermal Resistance Junction to Case	$R_{\theta\text{JC}}$	-	3.0(per leg)	$^{\circ}\text{C/W}$
			1.5(per device)	
Approximate Weight	wt	-	0.39	g
Case Style	DPAK			

**Ratings and Characteristics Curves**

Figure 1 Typical Forward Characteristics

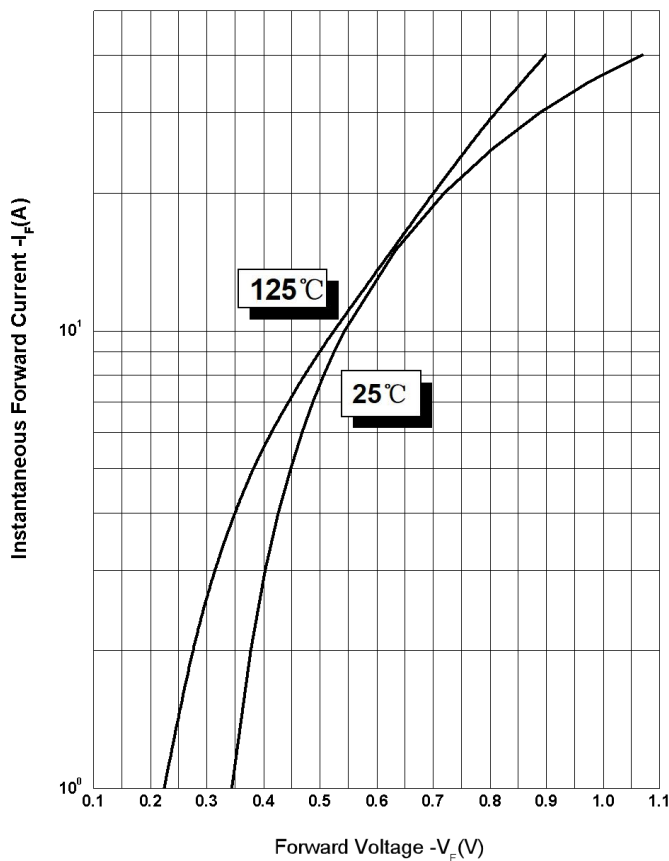


Figure 2 Typical Reverse Characteristics

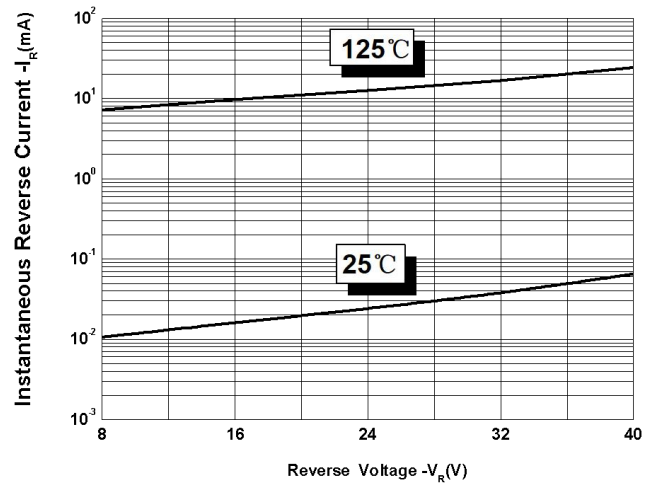
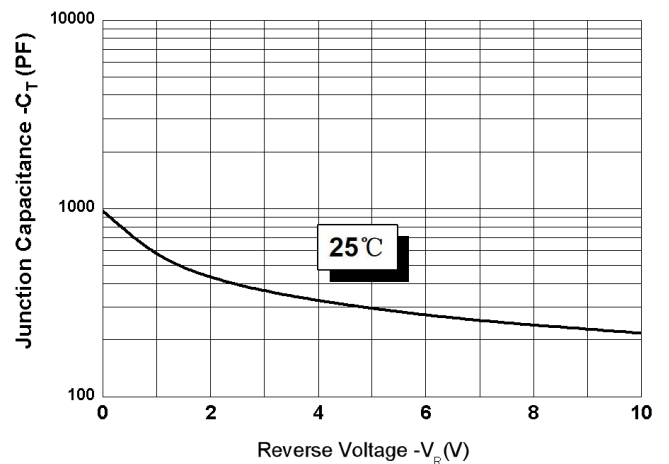
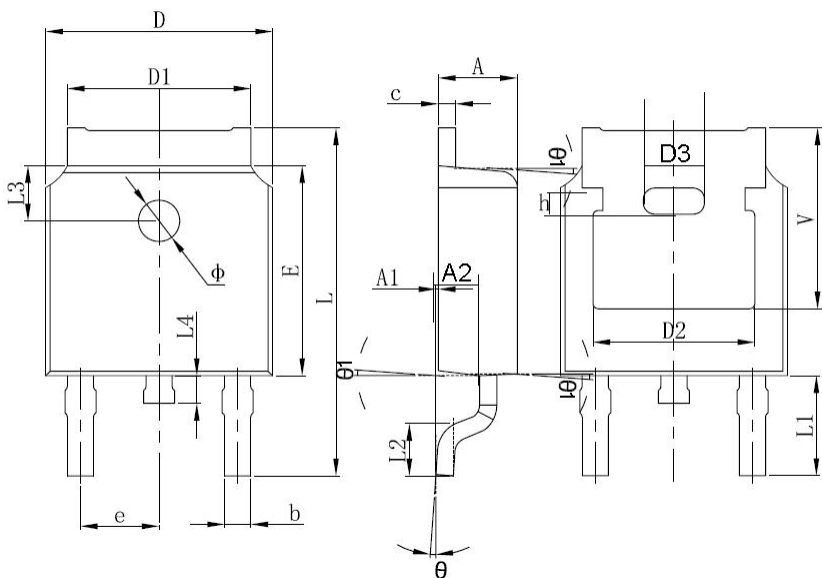


Figure 3 Typical Junction Capacitance



**Mechanical Dimensions DPAK**


Symbol	Dimensions in millimeters		
	Min.	Typical	Max.
A	2.18	-	2.39
A1	-	-	0.13
b	0.64	-	0.89
c	0.46	-	0.89
D	6.35	-	6.73
D1	4.95	-	5.46
D2	4.32	-	-
E	5.97	6.1	6.22
e	2.29BSC		
L	9.4	-	10.41
L1	2.90 REF.		
L2	1.4	1.52	1.78
L3	1.60 REF.		
L4	-	-	1.02
Φ	1.1	-	1.3
θ	0°	-	10°
V	5.21	-	-

The outline from different package houses may have slight differences. So the outline above is just schematic. The dimensions are controlled per specifications.

**Ordering Information**

Device	Package	Shipping
12CWQ04FN	DPAK (Pb-Free)	2500pcs / reel
12CWQ04FNTR	DPAK (Pb-Free)	2500pcs / reel

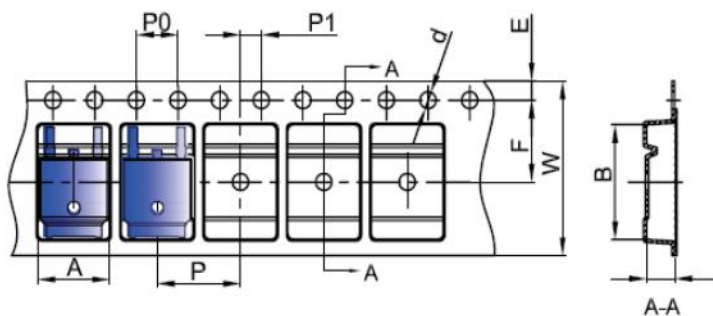
For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

**Marking Diagram**


Where XXXXX is YYWWL

- 12 = Forward Current (12A)
- CW = Configuration
- Q = Device Type
- 04 = Reverse Voltage (40V)
- FN = Package type
- SSG = SSG
- YY = Year
- WW = Week
- L = Lot Number

**Cautions:** Molding resin  
Epoxy resin UL:94V-0

**Carrier Tape Specification DPAK**


SYMBOL	Millimeters	
	Min.	Max.
A	6.80	7.00
B	10.40	10.60
C	2.60	2.80
d	Φ1.45	Φ1.65
E	1.65	1.85
F	7.40	7.60
P0	3.90	4.10
P	7.90	8.10
P1	1.90	2.10
W	15.90	16.30

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